Notice for TAIYO YUDEN Products

Please read this notice before using the TAIYO YUDEN products.

⚠ REMINDERS

Product Information in this Catalog

Product information in this catalog is as of March 2023. All of the contents specified herein and production status of the products listed in this catalog are subject to change without notice due to technical improvement of our products, etc. Therefore, please check for the latest information carefully before practical application or use of our products.

Please note that TAIYO YUDEN shall not be in any way responsible for any damages and defects in products or equipment incorporating our products, which are caused under the conditions other than those specified in this catalog or individual product specification sheets.

Approval of Product Specifications

Please contact TAIYO YUDEN for further details of product specifications as the individual product specification sheets are available. When using our products, please be sure to approve our product specifications or make a written agreement on the product specification with TAIYO YUDEN in advance.

Pre-Evaluation in the Actual Equipment and Conditions

Please conduct validation and verification of our products in actual conditions of mounting and operating environment before using our products.

Limited Application

1. Equipment Intended for Use

The products listed in this catalog are intended for general-purpose and standard use in general electronic equipment for consumer (e.g., AV equipment, OA equipment, home electric appliances, office equipment, information and communication equipment including, without limitation, mobile phone, and PC) and other equipment specified in this catalog or the individual product specification sheets, or the equipment approved separately by TAIYO YUDEN.
TAIYO YUDEN has the product series intended for use in the following equipment. Therefore, when using our products for these equipment, please check available applications specified in this catalog or the individual product specification sheets and use the corresponding products.

Application	Product Series		Quality Grade *3
	Equipment *1	Category (Part Number Code *2)	
Automotive	Automotive Electronic Equipment (POWERTRAIN, SAFETY)	A	1
	Automotive Electronic Equipment (BODY & CHASSIS, INFOTAINMENT)	C	2
Industrial	Telecommunications Infrastructure and Industrial Equipment	B	2
Medical	Medical Devices classified as GHTF Class C (Japan Class III)	M	2
	Medical Devices classified as GHTF Classes A or B (Japan Classes I or II)	L	3
Consumer	General Electronic Equipment	S	3
	Only for Mobile Devices *4	E	4

*Notes: 1. Based on the general specifications required for electronic components for such equipment, which are recognized by TAIYO YUDEN, the use of each product series for the equipment is recommended. Please be sure to contact TAIYO YUDEN before using our products for equipment other than those covered by the product series.
2. On each of our part number, the 2nd code from the left is a code indicating the “Category” as shown in the above table. For details, please check the explanatory materials regarding the part numbering system of each of our products.
3. Each product series is assigned a “Quality Grade” from 1 to 4 in order of higher quality. Please do not incorporate a product into any equipment with a higher Quality Grade than the Quality Grade of such product without the prior written consent of TAIYO YUDEN.
4. The applications covered by this product series are limited to mobile devices (smartphone, tablet PC, smartwatch, handheld game console, etc.) among general electronic equipment for consumer. The design, specifications and operating environment, etc. differ from those of the product series for "General Electronic Equipment" (Category: S), so please check the individual product specification sheets for details. The product series for "General Electronic Equipment" (Category: S) can also be used for mobile devices.

▶ This catalog contains the typical specification only due to the limitation of space. When you consider the purchase of our products, please check our product specification sheets. For details of each product (characteristics graph, reliability information, precautions for use, and so on), see our website (http://www.ty-top.com/) .

2. Equipment Requiring Inquiry

Please be sure to contact TAIYO YUDEN for further information before using the products listed in this catalog for the following equipment (excluding intended equipment as specified in this catalog or the individual product specification sheets) which may cause loss of human life, bodily injury, serious property damage and/or serious public impact due to a failure or defect of the products and/or malfunction attributed thereto.

(1) Transportation equipment (automotive powertrain control system, train control system, and ship control system, etc.)
(2) Traffic signal equipment
(3) Disaster prevention equipment, crime prevention equipment
(4) Medical devices classified as GHTF Class C (Japan Class III)
(5) Highly public information network equipment, data-processing equipment (telephone exchange, and base station, etc.)
(6) Any other equipment requiring high levels of quality and/or reliability equal to the equipment listed above

3. Equipment Prohibited for Use

Please do not incorporate our products into the following equipment requiring extremely high levels of safety and/or reliability.

(1) Aerospace equipment (artificial satellite, rocket, etc.)
(2) Aviation equipment *1
(3) Medical devices classified as GHTF Class D (Japan Class IV), implantable medical devices *2
(4) Power generation control equipment (nuclear power, hydroelectric power, thermal power plant control system, etc.)
(5) Undersea equipment (submarine repeating equipment, etc.)
(6) Military equipment
(7) Any other equipment requiring extremely high levels of safety and/or reliability equal to the equipment listed above

*Notes: 1. There is a possibility that our products can be used only for aviation equipment that does not directly affect the safe operation of aircraft (e.g., in-flight entertainment, cabin light, electric seat, cooking equipment) if such use meets requirements specified separately by TAIYO YUDEN. Please be sure to contact TAIYO YUDEN for further information before using our products for such aviation equipment.

2. Implantable medical devices contain not only internal unit which is implanted in a body, but also external unit which is connected to the internal unit.

4. Limitation of Liability

Please note that unless you obtain prior written consent of TAIYO YUDEN, TAIYO YUDEN shall not be in any way responsible for any damages incurred by you or third parties arising from use of the products listed in this catalog for any equipment that is not intended for use by TAIYO YUDEN, or any equipment requiring inquiry to TAIYO YUDEN or prohibited for use by TAIYO YUDEN as described above.

Safety Design

When using our products for high safety and/or reliability-required equipment or circuits, please fully perform safety and/or reliability evaluation. In addition, please install (i) systems equipped with a protection circuit and a protection device and/or (ii) systems equipped with a redundant circuit or other system to prevent an unsafe status in the event of a single fault for a failsafe design to ensure safety.

Intellectual Property Rights

Information contained in this catalog is intended to convey examples of typical performances and/or applications of our products and is not intended to make any warranty with respect to the intellectual property rights or any other related rights of TAIYO YUDEN or any third parties nor grant any license under such rights.

Limited Warranty

Please note that the scope of warranty for our products is limited to the delivered our products themselves conforming to the product specifications specified in the individual product specification sheets, and TAIYO YUDEN shall not be in any way responsible for any damages resulting from a failure or defect in our products. Notwithstanding the foregoing, if there is a written agreement (e.g., supply and purchase agreement, quality assurance agreement) signed by TAIYO YUDEN and your company, TAIYO YUDEN will warrant our products in accordance with such agreement, provided, however, that our products shall be used for general-purpose and standard use in the equipment specified in this catalog or the individual product specification sheets.

TAIYO YUDEN's Official Sales Channel

The contents of this catalog are applicable to our products which are purchased from our sales offices or authorized distributors (hereinafter "TAIYO YUDEN's official sales channel"). Please note that the contents of this catalog are not applicable to our products purchased from any seller other than TAIYO YUDEN's official sales channel.

Caution for Export

Some of our products listed in this catalog may require specific procedures for export according to "U.S. Export Administration Regulations", "Foreign Exchange and Foreign Trade Control Law" of Japan, and other applicable regulations. Should you have any questions on this matter, please contact our sales staff.

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Industrial Application Guide

We have the product series (the 2nd code from the left side of the part number is “B”) intended for use in telecommunications infrastructure and industrial equipment (its typical examples are as shown in the table below). Therefore, when using our products for these equipment, please check it carefully by referring to the part number or the individual product specification sheets and use the corresponding product series. Should you have any questions on this matter, please contact us.

Product Series (The 2nd Code from the Left Side of the Part Number)	Category	Telecommunications Infrastructure and Industrial Equipment (Typical Example)
B	Telecommunications Infrastructure	• Base Station • Optical Transceiver • Router/Switch (Carrier-Grade) • UPS (Uninterruptible Power Supply), etc.
	Factory Automation	• PLC (Programmable Logic Controller) • Servomotor/Servo Driver • Industry Robot, etc.
	Measurement	• Gas Meter • Water Meter • Flow Meter • Pressure Gauge Meter • Magnetometer • Thermometer, etc.
	Electric Power Apparatus	• Power Conditioner (Solar Power System) • Smart Meter • GFCI (Ground Fault Circuit Interrupter) • Electric Vehicle Charging Station, etc.

▶ This catalog contains the typical specification only due to the limitation of space. When you consider the purchase of our products, please check our product specification sheets. For details of each product (characteristics graph, reliability information, precautions for use, and so on), see our website (http://www.ty-top.com/) .

Multilayer Ceramic Capacitors for Telecommunications Infrastructure and Industrial Equipment

REFLOW

■PART NUMBER

M	B	A	S	T	3	1	L	S	B	5	1	0	6	K	T	N	A	0	1
①				②	③		④	⑤	⑥		⑦			⑧	⑨	⑩			

①Series

Code (1)(2)(3)(4)	
MBAS	Multilayer Ceramic Capacitor (High dielectric type) for Telecommunications Infrastructure and Industrial Equipment Multilayer Ceramic Capacitor (Temperature compensating type) for Telecommunications Infrastructure and Industrial Equipment Medium-High voltage Multilayer Ceramic Capacitor for Telecommunications Infrastructure and Industrial Equipment
MBAR	High frequency/Low loss Medium-High Voltage Multilayer Ceramic Capacitor for Telecommunications Infrastructure and Industrial Equipment
MBJC	Soft Termination Multilayer Ceramic Capacitor for Telecommunications Infrastructure and Industrial Equipment
MBRL	LW Reversal Decoupling Low ESL Capacitor (LWDC™) for Telecommunications Infrastructure and Industrial Equipment

(1) Product Group

Code	
M	Multilayer Ceramic Capacitor

(2) Category

Code	Recommended equipment	Quality Grade
B	Telecommunications Infrastructure and Industrial Equipment	2

(3) Type

Code	
A	2 terminals
J	Soft Termination
R	LW reversal

(4) Features, Characteristics

Code	
S	Standard/General
R	High frequency/Low loss
C	Internal code (Soft Termination)
L	Low ESL

②Rated voltage

Code	Rated voltage[VDC]
A	4
J	6.3
L	10
E	16
T	25
G	35
U	50
H	100
Q	250
S	630

④Thickness

Code	Thickness[mm]
3	0.3
5	0.5
7	0.7
8	0.8
9	0.85
Q	1.15
G	1.25
L	1.6
N	1.9 (0.088 max ※)
M	2.5

Note : ※LW reverse type(MBRL)

③Dimension(L×W)

Code	L×W [mm]	JIS(mm)	EIA(inch)
06	0.6 × 0.3	0603	0201
10	1.0 × 0.5	1005	0402
	0.52× 1.0 ※	0510	0204
16	1.6 × 0.8	1608	0603
	0.8 × 1.6 ※	0816	0306
21	2.0 × 1.25	2012	0805
	1.25× 2.0 ※	1220	0508
31	3.2 × 1.6	3216	1206
32	3.2 × 2.5	3225	1210
45	4.5 × 3.2	4532	1812

Note : ※LW reverse type(MBRL)

⑤Dimension tolerance

Code	Dimension code	L[mm]	W[mm]	T[mm]	Thickness code
A	10	1.0±0.10	0.5±0.10	0.5±0.10	5
	16	1.6+0.15/−0.05	0.8+0.15/−0.05	0.8+0.15/−0.05	8
	21	2.0+0.15/−0.05	1.25+0.15/−0.05	1.25+0.15/−0.05	G
	31	3.2±0.20	1.6±0.20	1.15±0.20	Q
				1.6±0.20	L
	32	3.2±0.30	2.5±0.30	2.5±0.30	M
B	10	1.0+0.15/−0.05	0.5+0.15/−0.05	0.5+0.15/−0.05	5
	16	1.6+0.20/−0	0.8+0.20/−0	0.8+0.20/−0	8
	21	2.0+0.20/−0	1.25+0.20/−0	1.25+0.20/−0	G
	31	3.2±0.30	1.6±0.30	1.6±0.30	L
C	10	1.0+0.20/−0	0.5+0.20/−0	0.5+0.20/−0	5
	16	1.6+0.25/−0	0.8+0.25/−0	0.8+0.25/−0	8
	21	2.0+0.25/−0	1.25+0.25/−0	1.25+0.25/−0	G
D	21	2.0+0.30/−0	1.25+0.30/−0	1.25+0.30/−0	G
H	31	3.2±0.15	1.6±0.15	1.15±0.10	Q
J	21	2.0+0.15/−0.05	1.25+0.15/−0.05	0.85±0.10	9
L	21	2.0+0.20/−0	1.25+0.20/−0	0.85±0.10	9
	32	3.2±0.50	2.5±0.30	2.5±0.30	M
N	21	2.0±0.15	1.25±0.15	0.85±0.15	9
S	06	0.6±0.03	0.3±0.03	0.3±0.03	3
	10	1.0±0.05	0.5±0.05	0.5±0.05	5
		0.52±0.05 ※	1.0±0.05	0.3±0.05	3
	16	1.6±0.10	0.8±0.10	0.7±0.10	7
				0.8±0.10	8
		0.8±0.10 ※	1.6±0.10	0.5±0.05	5
	21	2.0±0.10	1.25±0.10	0.85±0.10	9
				1.25±0.10	G
		1.25±0.15 ※	2.0±0.15	0.85±0.10	9
	31	3.2±0.15	1.6±0.15	1.6±0.20	L
	32	3.2±0.30	2.5±0.20	1.9±0.20	N
				2.5±0.20	M
	45	4.5±0.40	3.2±0.30	2.5±0.20	M

Note :※LW reverse type(MBRL)

⑥Temperature characteristics code

■High dielectric type

Code	Applicable standard		Temperature range[℃]	Ref. Temp.[℃]	Capacitance change	Capacitance tolerance	Tolerance code
B5	EIA	X5R	−55～＋ 85	25	±15%	±10%	K
						±20%	M
C6	EIA	X6S	−55～＋105	25	±22%	±10%	K
						±20%	M
B7	EIA	X7R	−55～＋125	25	±15%	±10%	K
						±20%	M
C7	EIA	X7S	−55～＋125	25	±22%	±10%	K
						±20%	M
D7	EIA	X7T	−55～＋125	25	＋22%/−33%	±10%	K
						±20%	M

■Temperature compensating type

Code	Applicable standard		Temperature range[℃]	Ref. Temp.[℃]	Capacitance change	Capacitance tolerance	Tolerance code
CG	JIS	CG	−55～＋125	20	0±30ppm/℃	±0.05pF	A
						±0.1pF	B
						±0.25pF	C
	EIA	C0G		25		±0.5pF	D
						±2%	G
						±5%	J
CH	JIS	CH	−55～＋125	20	0±60ppm/℃	±0.25pF	C
						±0.5pF	D
	EIA	C0H		25		±5%	J
CJ	JIS	CJ	−55～＋125	20	0±120ppm/℃	±0.25pF	C
	EIA	C0J		25			
CK	JIS	CK	−55～＋125	20	0±250ppm/℃	±0.25pF	C
	EIA	C0K		25			

⑦Nominal capacitance

Code (example)	Nominal capacitance
0R5	0.5pF
010	1pF
100	10pF
101	100pF
102	1,000pF
103	0.01μF
104	0.1μF
105	1μF
106	10μF
107	100μF

Note : R＝Decimal point

⑧Capacitance tolerance

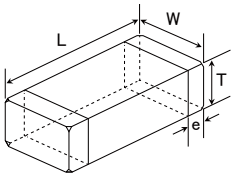
Code	Capacitance tolerance
A	±0.05pF
B	±0.1pF
C	±0.25pF
D	±0.5pF
G	±2%
J	±5%
K	±10%
M	±20%

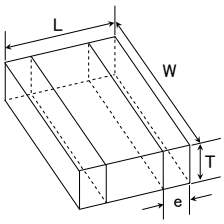
⑨Packaging

Code	Packaging
F	φ178mm Taping (2mm pitch)
R	φ178mm Embossed Taping (4mm pitch)
T	φ178mm Taping (4mm pitch)
P	φ178mm Taping (4mm pitch, 1000 pcs/reel) 3225 type(Thickness code M)

⑩Internal code

■STANDARD EXTERNAL DIMENSIONS





※LW reverse type

Type	JIS (mm)	EIA (inch)	Dimension [mm] (inch)				
			L	W	T	*1	e
MBAS□06	0603	0201	0.6±0.03 (0.024±0.001)	0.3±0.03 (0.012±0.001)	0.3±0.03 (0.012±0.001)	3	0.15±0.05 (0.006±0.002)
MBAR□10 MBAS□10	1005	0402	1.0±0.05 (0.039±0.002)	0.5±0.05 (0.020±0.002)	0.5±0.05 (0.020±0.002)	5	0.25±0.10 (0.010±0.004)
MBRL□10 ※	0510	0204	0.52±0.05 (0.020±0.002)	1.0±0.05 (0.039±0.002)	0.3±0.05 (0.012±0.002)	3	0.18±0.08 (0.007±0.003)
MBAS□16 MBAR□16	1608	0603	1.6±0.10 (0.063±0.004)	0.8±0.10 (0.031±0.004)	0.7±0.10 (0.028±0.004)	7	0.35±0.25 (0.014±0.010)
					0.8±0.10 (0.031±0.004)	8	
MBJC□16	1608	0603	1.6±0.10 (0.063±0.004)	0.8±0.10 (0.031±0.004)	0.8±0.10 (0.031±0.004)	8	0.35+0.3/−0.25 (0.014+0.012/−0.010)
MBRL□16 ※	0816	0306	0.8±0.10 (0.031±0.004)	1.6±0.10 (0.063±0.004)	0.5±0.05 (0.020±0.002)	5	0.25±0.15 (0.010±0.006)
MBAS□21 MBAR□21	2012	0805	2.0±0.10 (0.079±0.004)	1.25±0.10 (0.049±0.004)	0.85±0.10 (0.033±0.004)	9	0.5±0.25 (0.020±0.010)
					1.25±0.10 (0.049±0.004)	G	
MBJC□21	2012	0805	2.0±0.10 (0.079±0.004)	1.25±0.10 (0.049±0.004)	0.85±0.10 (0.033±0.004)	9	0.5+0.35/−0.25 (0.020+0.014/−0.010)
					1.25±0.10 (0.049±0.004)	G	
MBRL□21 ※	1220	0508	1.25±0.15 (0.049±0.006)	2.0±0.15 (0.079±0.006)	0.85±0.10 (0.033±0.004)	9	0.3±0.2 (0.012±0.008)
MBAS□31	3216	1206	3.2±0.15 (0.126±0.006)	1.6±0.15 (0.063±0.006)	1.15±0.10 (0.045±0.004)	Q	0.5+0.35/−0.25 (0.020+0.014/−0.010)
					1.6±0.20 (0.063±0.008)	L	
MBJC□31	3216	1206	3.2±0.15 (0.126±0.006)	1.6±0.15 (0.063±0.006)	1.15±0.10 (0.045±0.004)	Q	0.6+0.4/−0.3 (0.024+0.016/−0.012)
					1.6±0.20 (0.063±0.008)	L	
MBAS□32	3225	1210	3.2±0.30 (0.126±0.012)	2.5±0.20 (0.098±0.008)	1.9±0.20 (0.075±0.008)	N	0.6±0.3 (0.024±0.012)
					2.5±0.20 (0.098±0.008)	M	
MBJC□32	3225	1210	3.2±0.30 (0.126±0.012)	2.5±0.20 (0.098±0.008)	1.9±0.20 (0.075±0.008)	N	0.6+0.4/−0.3 (0.024+0.016/−0.012)
					2.5±0.20 (0.098±0.008)	M	
MBAS□45	4532	1812	4.5±0.40 (0.177±0.016)	3.2±0.30 (0.126±0.012)	2.5±0.20 (0.098±0.008)	M	0.9±0.6 (0.035±0.024)

Note :※LW reverse type(MBRL), *1.Thickness code

■STANDARD QUANTITY

Type			Thickness		Standard quantity[pcs]	
Code	JIS(mm)	EIA(inch)	[mm]	Code	Paper tape	Embossed tape
06	0603	0201	0.3	3	15000	—
10	1005	0402	0.5	5	10000	—
	0510 ※	0204 ※	0.3	3		
16	1608	0603	0.7	7	4000	—
			0.8	8		
			0.8	8	3000 (Soft Termination)	3000 (Soft Termination)
	0816 ※	0306 ※	0.5	5	—	4000
21	2012	0805	0.85	9	4000	—
			1.25	G	—	3000
			1.25	G	—	2000 (Soft Termination)
	1220 ※	0508 ※	0.85	9	4000	—
31	3216	1206	1.15	Q	—	3000
			1.6	L	—	2000
32	3225	1210	1.9	N	—	2000
			2.5	M	—	500(T), 1000(P)
45	4532	1812	2.5	M	—	500

Note : ※.LW Reverse type(MBRL)

■PART NUMBER

High frequency/Low loss Medium-High Voltage Multilayer Ceramic Capacitors for Telecommunications Infrastructure and Industrial Equipment

●1005TYPE

【Temperature Characteristic CG : CG/C0G(－55～＋125℃)】 0.5mm Thickness

New part number	Old part number (for reference)	Rated voltage [V]	Temperature characteristics		Capacitance [F]	Capacitance tolerance	Q [at 1MHz] (Min)	HTLT Rated voltage x %	Thickness*1 [mm]	Note
MBARQ105SCG0R5□FRA01	QVS105 CG0R5□VHF		CG	C0G	0.5 p	±0.1pF, ±0.25pF	810	200	0.5±0.05	
MBARQ105SCG0R6□FRA01	QVS105 CG0R6□VHF		CG	C0G	0.6 p	±0.1pF, ±0.25pF	812	200	0.5±0.05	
MBARQ105SCG0R7□FRA01	QVS105 CG0R7□VHF		CG	C0G	0.7 p	±0.1pF, ±0.25pF	814	200	0.5±0.05	
MBARQ105SCGR75□FRA01	QVS105 CGR75□VHF		CG	C0G	0.75 p	±0.1pF, ±0.25pF	815	200	0.5±0.05	
MBARQ105SCG0R8□FRA01	QVS105 CG0R8□VHF		CG	C0G	0.8 p	±0.1pF, ±0.25pF	816	200	0.5±0.05	
MBARQ105SCG0R9□FRA01	QVS105 CG0R9□VHF		CG	C0G	0.9 p	±0.1pF, ±0.25pF	818	200	0.5±0.05	
MBARQ105SCG010□FRA01	QVS105 CG010□VHF		CG	C0G	1 p	±0.1pF, ±0.25pF	820	200	0.5±0.05	
MBARQ105SCG1R1□FRA01	QVS105 CG1R1□VHF		CG	C0G	1.1 p	±0.1pF, ±0.25pF	822	200	0.5±0.05	
MBARQ105SCG1R2□FRA01	QVS105 CG1R2□VHF		CG	C0G	1.2 p	±0.1pF, ±0.25pF	824	200	0.5±0.05	
MBARQ105SCG1R3□FRA01	QVS105 CG1R3□VHF		CG	C0G	1.3 p	±0.1pF, ±0.25pF	826	200	0.5±0.05	
MBARQ105SCG1R5□FRA01	QVS105 CG1R5□VHF		CG	C0G	1.5 p	±0.1pF, ±0.25pF	830	200	0.5±0.05	
MBARQ105SCG1R6□FRA01	QVS105 CG1R6□VHF		CG	C0G	1.6 p	±0.1pF, ±0.25pF	832	200	0.5±0.05	
MBARQ105SCG1R8□FRA01	QVS105 CG1R8□VHF		CG	C0G	1.8 p	±0.1pF, ±0.25pF	836	200	0.5±0.05	
MBARQ105SCG020□FRA01	QVS105 CG020□VHF		CG	C0G	2 p	±0.1pF, ±0.25pF	840	200	0.5±0.05	
MBARQ105SCG2R2□FRA01	QVS105 CG2R2□VHF		CG	C0G	2.2 p	±0.1pF, ±0.25pF	844	200	0.5±0.05	
MBARQ105SCG2R4□FRA01	QVS105 CG2R4□VHF		CG	C0G	2.4 p	±0.1pF, ±0.25pF	848	200	0.5±0.05	
MBARQ105SCG2R7□FRA01	QVS105 CG2R7□VHF		CG	C0G	2.7 p	±0.1pF, ±0.25pF	854	200	0.5±0.05	
MBARQ105SCG030□FRA01	QVS105 CG030□VHF		CG	C0G	3 p	±0.1pF, ±0.25pF	860	200	0.5±0.05	
MBARQ105SCG3R3□FRA01	QVS105 CG3R3□VHF		CG	C0G	3.3 p	±0.1pF, ±0.25pF	866	200	0.5±0.05	
MBARQ105SCG3R6□FRA01	QVS105 CG3R6□VHF		CG	C0G	3.6 p	±0.1pF, ±0.25pF	872	200	0.5±0.05	
MBARQ105SCG3R9□FRA01	QVS105 CG3R9□VHF		CG	C0G	3.9 p	±0.1pF, ±0.25pF	878	200	0.5±0.05	
MBARQ105SCG4R3□FRA01	QVS105 CG4R3□VHF	250	CG	C0G	4.3 p	±0.1pF, ±0.25pF	886	200	0.5±0.05	
MBARQ105SCG4R7□FRA01	QVS105 CG4R7□VHF		CG	C0G	4.7 p	±0.1pF, ±0.25pF	894	200	0.5±0.05	
MBARQ105SCG5R1□FRA01	QVS105 CG5R1□VHF		CG	C0G	5.1 p	±0.25pF, ±0.5pF	902	200	0.5±0.05	
MBARQ105SCG5R6□FRA01	QVS105 CG5R6□VHF		CG	C0G	5.6 p	±0.25pF, ±0.5pF	912	200	0.5±0.05	
MBARQ105SCG6R2□FRA01	QVS105 CG6R2□VHF		CG	C0G	6.2 p	±0.25pF, ±0.5pF	924	200	0.5±0.05	
MBARQ105SCG6R8□FRA01	QVS105 CG6R8□VHF		CG	C0G	6.8 p	±0.25pF, ±0.5pF	936	200	0.5±0.05	
MBARQ105SCG7R5□FRA01	QVS105 CG7R5□VHF		CG	C0G	7.5 p	±0.25pF, ±0.5pF	950	200	0.5±0.05	
MBARQ105SCG8R2□FRA01	QVS105 CG8R2□VHF		CG	C0G	8.2 p	±0.25pF, ±0.5pF	964	200	0.5±0.05	
MBARQ105SCG9R1□FRA01	QVS105 CG9R1□VHF		CG	C0G	9.1 p	±0.25pF, ±0.5pF	982	200	0.5±0.05	
MBARQ105SCG100JFRA01	QVS105 CG100JVHF		CG	C0G	10 p	±5%	1000	200	0.5±0.05	
MBARQ105SCG110JFRA01	QVS105 CG110JVHF		CG	C0G	11 p	±5%	1020	200	0.5±0.05	
MBARQ105SCG120JFRA01	QVS105 CG120JVHF		CG	C0G	12 p	±5%	1040	200	0.5±0.05	
MBARQ105SCG130JFRA01	QVS105 CG130JVHF		CG	C0G	13 p	±5%	1060	200	0.5±0.05	
MBARQ105SCG150JFRA01	QVS105 CG150JVHF		CG	C0G	15 p	±5%	1100	200	0.5±0.05	
MBARQ105SCG160JFRA01	QVS105 CG160JVHF		CG	C0G	16 p	±5%	1120	200	0.5±0.05	
MBARQ105SCG180JFRA01	QVS105 CG180JVHF		CG	C0G	18 p	±5%	1160	200	0.5±0.05	
MBARQ105SCG200JFRA01	QVS105 CG200JVHF		CG	C0G	20 p	±5%	1200	200	0.5±0.05	
MBARQ105SCG220JFRA01	QVS105 CG220JVHF		CG	C0G	22 p	±5%	1240	200	0.5±0.05	
MBARQ105SCG240JFRA01	QVS105 CG240JVHF		CG	C0G	24 p	±5%	1280	200	0.5±0.05	
MBARQ105SCG270JFRA01	QVS105 CG270JVHF		CG	C0G	27 p	±5%	1340	200	0.5±0.05	
MBARQ105SCG300JFRA01	QVS105 CG300JVHF		CG	C0G	30 p	±5%	1400	200	0.5±0.05	
MBARQ105SCG330JFRA01	QVS105 CG330JVHF		CG	C0G	33 p	±5%	1400	200	0.5±0.05	

■PART NUMBER

●1608TYPE

【Temperature Characteristic CG : CG/C0G(－55～＋125℃)】 0.7mm Thickness

New part number	Old part number (for reference)	Rated voltage [V]	Temperature characteristics		Capacitance [F]	Capacitance tolerance	Q [at 1MHz] (Min)	HTLT Rated voltage x %	Thickness*1 [mm]	Note
MBARQ167SCG0R2□TRA01	QVS107 CG0R2□CHT	250	CG	C0G	0.2 p	±0.05pF, ±0.1pF	804	200	0.7±0.10	
MBARQ167SCG0R3□TRA01	QVS107 CG0R3□CHT		CG	C0G	0.3 p	±0.05pF, ±0.1pF	806	200	0.7±0.10	
MBARQ167SCG0R4□TRA01	QVS107 CG0R4□CHT		CG	C0G	0.4 p	±0.05pF, ±0.1pF	808	200	0.7±0.10	
MBARQ167SCG0R5□TRA01	QVS107 CG0R5□CHT		CG	C0G	0.5 p	±0.1pF, ±0.25pF	810	200	0.7±0.10	
MBARQ167SCG0R6□TRA01	QVS107 CG0R6□CHT		CG	C0G	0.6 p	±0.1pF, ±0.25pF	812	200	0.7±0.10	
MBARQ167SCG0R7□TRA01	QVS107 CG0R7□CHT		CG	C0G	0.7 p	±0.1pF, ±0.25pF	814	200	0.7±0.10	
MBARQ167SCGR75□TRA01	QVS107 CGR75□CHT		CG	C0G	0.75 p	±0.1pF, ±0.25pF	815	200	0.7±0.10	
MBARQ167SCG0R8□TRA01	QVS107 CG0R8□CHT		CG	C0G	0.8 p	±0.1pF, ±0.25pF	816	200	0.7±0.10	
MBARQ167SCG0R9□TRA01	QVS107 CG0R9□CHT		CG	C0G	0.9 p	±0.1pF, ±0.25pF	818	200	0.7±0.10	
MBARQ167SCG010□TRA01	QVS107 CG010□CHT		CG	C0G	1 p	±0.1pF, ±0.25pF	820	200	0.7±0.10	
MBARQ167SCG1R1□TRA01	QVS107 CG1R1□CHT		CG	C0G	1.1 p	±0.1pF, ±0.25pF	822	200	0.7±0.10	
MBARQ167SCG1R2□TRA01	QVS107 CG1R2□CHT		CG	C0G	1.2 p	±0.1pF, ±0.25pF	824	200	0.7±0.10	
MBARQ167SCG1R3□TRA01	QVS107 CG1R3□CHT		CG	C0G	1.3 p	±0.1pF, ±0.25pF	826	200	0.7±0.10	
MBARQ167SCG1R5□TRA01	QVS107 CG1R5□CHT		CG	C0G	1.5 p	±0.1pF, ±0.25pF	830	200	0.7±0.10	
MBARQ167SCG1R6□TRA01	QVS107 CG1R6□CHT		CG	C0G	1.6 p	±0.1pF, ±0.25pF	832	200	0.7±0.10	
MBARQ167SCG1R8□TRA01	QVS107 CG1R8□CHT		CG	C0G	1.8 p	±0.1pF, ±0.25pF	836	200	0.7±0.10	
MBARQ167SCG020□TRA01	QVS107 CG020□CHT		CG	C0G	2 p	±0.1pF, ±0.25pF	840	200	0.7±0.10	
MBARQ167SCG2R2□TRA01	QVS107 CG2R2□CHT		CG	C0G	2.2 p	±0.1pF, ±0.25pF	844	200	0.7±0.10	
MBARQ167SCG2R4□TRA01	QVS107 CG2R4□CHT		CG	C0G	2.4 p	±0.1pF, ±0.25pF	848	200	0.7±0.10	
MBARQ167SCG2R7□TRA01	QVS107 CG2R7□CHT		CG	C0G	2.7 p	±0.1pF, ±0.25pF	854	200	0.7±0.10	
MBARQ167SCG030□TRA01	QVS107 CG030□CHT		CG	C0G	3 p	±0.1pF, ±0.25pF	860	200	0.7±0.10	
MBARQ167SCG3R3□TRA01	QVS107 CG3R3□CHT		CG	C0G	3.3 p	±0.1pF, ±0.25pF	866	200	0.7±0.10	
MBARQ167SCG3R6□TRA01	QVS107 CG3R6□CHT		CG	C0G	3.6 p	±0.1pF, ±0.25pF	872	200	0.7±0.10	
MBARQ167SCG3R9□TRA01	QVS107 CG3R9□CHT		CG	C0G	3.9 p	±0.1pF, ±0.25pF	878	200	0.7±0.10	
MBARQ167SCG4R3□TRA01	QVS107 CG4R3□CHT		CG	C0G	4.3 p	±0.1pF, ±0.25pF	886	200	0.7±0.10	
MBARQ167SCG4R7□TRA01	QVS107 CG4R7□CHT		CG	C0G	4.7 p	±0.1pF, ±0.25pF	894	200	0.7±0.10	
MBARQ167SCG5R1□TRA01	QVS107 CG5R1□CHT		CG	C0G	5.1 p	±0.25pF,±0.5pF	902	200	0.7±0.10	
MBARQ167SCG5R6□TRA01	QVS107 CG5R6□CHT		CG	C0G	5.6 p	±0.25pF,±0.5pF	912	200	0.7±0.10	
MBARQ167SCG6R2□TRA01	QVS107 CG6R2□CHT		CG	C0G	6.2 p	±0.25pF,±0.5pF	924	200	0.7±0.10	
MBARQ167SCG6R8□TRA01	QVS107 CG6R8□CHT		CG	C0G	6.8 p	±0.25pF,±0.5pF	936	200	0.7±0.10	
MBARQ167SCG7R5□TRA01	QVS107 CG7R5□CHT		CG	C0G	7.5 p	±0.25pF,±0.5pF	950	200	0.7±0.10	
MBARQ167SCG8R2□TRA01	QVS107 CG8R2□CHT		CG	C0G	8.2 p	±0.25pF,±0.5pF	964	200	0.7±0.10	
MBARQ167SCG9R1□TRA01	QVS107 CG9R1□CHT		CG	C0G	9.1 p	±0.25pF,±0.5pF	982	200	0.7±0.10	
MBARQ167SCG100□TRA01	QVS107 CG100□CHT		CG	C0G	10 p	±2%, ±5%	1000	200	0.7±0.10	
MBARQ167SCG110JTRA01	QVS107 CG110JCHT		CG	C0G	11 p	±5%	1020	200	0.7±0.10	
MBARQ167SCG120JTRA01	QVS107 CG120JCHT		CG	C0G	12 p	±5%	1040	200	0.7±0.10	
MBARQ167SCG130JTRA01	QVS107 CG130JCHT		CG	C0G	13 p	±5%	1060	200	0.7±0.10	
MBARQ167SCG150JTRA01	QVS107 CG150JCHT		CG	C0G	15 p	±5%	1100	200	0.7±0.10	
MBARQ167SCG160JTRA01	QVS107 CG160JCHT		CG	C0G	16 p	±5%	1120	200	0.7±0.10	
MBARQ167SCG180JTRA01	QVS107 CG180JCHT		CG	C0G	18 p	±5%	1160	200	0.7±0.10	
MBARQ167SCG200JTRA01	QVS107 CG200JCHT		CG	C0G	20 p	±5%	1200	200	0.7±0.10	
MBARQ167SCG220JTRA01	QVS107 CG220JCHT		CG	C0G	22 p	±5%	1240	200	0.7±0.10	
MBARQ167SCG240JTRA01	QVS107 CG240JCHT		CG	C0G	24 p	±5%	1280	200	0.7±0.10	
MBARQ167SCG270JTRA01	QVS107 CG270JCHT		CG	C0G	27 p	±5%	1340	200	0.7±0.10	
MBARQ167SCG300JTRA01	QVS107 CG300JCHT		CG	C0G	30 p	±5%	1400	200	0.7±0.10	
MBARQ167SCG330JTRA01	QVS107 CG330JCHT		CG	C0G	33 p	±5%	1400	200	0.7±0.10	
MBARQ167SCG360JTRA01	QVS107 CG360JCHT		CG	C0G	36 p	±5%	1400	200	0.7±0.10	
MBARQ167SCG390JTRA01	QVS107 CG390JCHT		CG	C0G	39 p	±5%	1400	200	0.7±0.10	
MBARQ167SCG430JTRA01	QVS107 CG430JCHT		CG	C0G	43 p	±5%	1400	200	0.7±0.10	
MBARQ167SCG470JTRA01	QVS107 CG470JCHT		CG	C0G	47 p	±5%	1400	200	0.7±0.10	
MBARQ167SCG510JTRA01	QVS107 CG510JCHT		CG	C0G	51 p	±5%	1400	200	0.7±0.10	
MBARQ167SCG560JTRA01	QVS107 CG560JCHT		CG	C0G	56 p	±5%	1400	200	0.7±0.10	
MBARQ167SCG620JTRA01	QVS107 CG620JCHT		CG	C0G	62 p	±5%	1400	200	0.7±0.10	
MBARQ167SCG680JTRA01	QVS107 CG680JCHT		CG	C0G	68 p	±5%	1400	200	0.7±0.10	
MBARQ167SCG750JTRA01	QVS107 CG750JCHT		CG	C0G	75 p	±5%	1400	200	0.7±0.10	
MBARQ167SCG820JTRA01	QVS107 CG820JCHT		CG	C0G	82 p	±5%	1400	200	0.7±0.10	
MBARQ167SCG910JTRA01	QVS107 CG910JCHT		CG	C0G	91 p	±5%	1400	200	0.7±0.10	
MBARQ167SCG101JTRA01	QVS107 CG101JCHT		CG	C0G	100 p	±5%	1400	200	0.7±0.10	

■PART NUMBER

●2012TYPE

【Temperature Characteristic CG : CG/C0G(－55～＋125℃)】 0.85mm Thickness

New part number	Old part number (for reference)	Rated voltage [V]	Temperature characteristics		Capacitance [F]	Capacitance tolerance	Q [at 1MHz] (Min)	HTLT Rated voltage x %	Thickness*1 [mm]	Note
MBARQ219SCG0R3□TRA01	QVS212 CG0R3□DHT		CG	C0G	0.3 p	±0.1pF, ±0.25pF,±0.5pF	806	200	0.85±0.10	
MBARQ219SCG0R4□TRA01	QVS212 CG0R4□DHT		CG	C0G	0.4 p	±0.1pF, ±0.25pF,±0.5pF	808	200	0.85±0.10	
MBARQ219SCG0R5□TRA01	QVS212 CG0R5□DHT		CG	C0G	0.5 p	±0.1pF, ±0.25pF	810	200	0.85±0.10	
MBARQ219SCG0R6□TRA01	QVS212 CG0R6□DHT		CG	C0G	0.6 p	±0.1pF, ±0.25pF	812	200	0.85±0.10	
MBARQ219SCG0R7□TRA01	QVS212 CG0R7□DHT		CG	C0G	0.7 p	±0.1pF, ±0.25pF	814	200	0.85±0.10	
MBARQ219SCGR75□TRA01	QVS212 CGR75□DHT		CG	C0G	0.75 p	±0.1pF, ±0.25pF	815	200	0.85±0.10	
MBARQ219SCG0R8□TRA01	QVS212 CG0R8□DHT		CG	C0G	0.8 p	±0.1pF, ±0.25pF	816	200	0.85±0.10	
MBARQ219SCG0R9□TRA01	QVS212 CG0R9□DHT		CG	C0G	0.9 p	±0.1pF, ±0.25pF	818	200	0.85±0.10	
MBARQ219SCG010□TRA01	QVS212 CG010□DHT		CG	C0G	1 p	±0.1pF, ±0.25pF	820	200	0.85±0.10	
MBARQ219SCG1R1□TRA01	QVS212 CG1R1□DHT		CG	C0G	1.1 p	±0.1pF, ±0.25pF	822	200	0.85±0.10	
MBARQ219SCG1R2□TRA01	QVS212 CG1R2□DHT		CG	C0G	1.2 p	±0.1pF, ±0.25pF	824	200	0.85±0.10	
MBARQ219SCG1R3□TRA01	QVS212 CG1R3□DHT		CG	C0G	1.3 p	±0.1pF, ±0.25pF	826	200	0.85±0.10	
MBARQ219SCG1R5□TRA01	QVS212 CG1R5□DHT		CG	C0G	1.5 p	±0.1pF, ±0.25pF	830	200	0.85±0.10	
MBARQ219SCG1R6□TRA01	QVS212 CG1R6□DHT		CG	C0G	1.6 p	±0.1pF, ±0.25pF	832	200	0.85±0.10	
MBARQ219SCG1R8□TRA01	QVS212 CG1R8□DHT		CG	C0G	1.8 p	±0.1pF, ±0.25pF	836	200	0.85±0.10	
MBARQ219SCG020□TRA01	QVS212 CG020□DHT		CG	C0G	2 p	±0.1pF, ±0.25pF	840	200	0.85±0.10	
MBARQ219SCG2R2□TRA01	QVS212 CG2R2□DHT		CG	C0G	2.2 p	±0.1pF, ±0.25pF	844	200	0.85±0.10	
MBARQ219SCG2R4□TRA01	QVS212 CG2R4□DHT		CG	C0G	2.4 p	±0.1pF, ±0.25pF	848	200	0.85±0.10	
MBARQ219SCG2R7□TRA01	QVS212 CG2R7□DHT		CG	C0G	2.7 p	±0.1pF, ±0.25pF	854	200	0.85±0.10	
MBARQ219SCG030□TRA01	QVS212 CG030□DHT		CG	C0G	3 p	±0.1pF, ±0.25pF	860	200	0.85±0.10	
MBARQ219SCG3R3□TRA01	QVS212 CG3R3□DHT		CG	C0G	3.3 p	±0.1pF, ±0.25pF	866	200	0.85±0.10	
MBARQ219SCG3R6□TRA01	QVS212 CG3R6□DHT		CG	C0G	3.6 p	±0.1pF, ±0.25pF	872	200	0.85±0.10	
MBARQ219SCG3R9□TRA01	QVS212 CG3R9□DHT		CG	C0G	3.9 p	±0.1pF, ±0.25pF	878	200	0.85±0.10	
MBARQ219SCG4R3□TRA01	QVS212 CG4R3□DHT		CG	C0G	4.3 p	±0.1pF, ±0.25pF	886	200	0.85±0.10	
MBARQ219SCG4R7□TRA01	QVS212 CG4R7□DHT		CG	C0G	4.7 p	±0.1pF, ±0.25pF	894	200	0.85±0.10	
MBARQ219SCG5R1□TRA01	QVS212 CG5R1□DHT		CG	C0G	5.1 p	±0.25pF, ±0.5pF	902	200	0.85±0.10	
MBARQ219SCG5R6□TRA01	QVS212 CG5R6□DHT		CG	C0G	5.6 p	±0.25pF, ±0.5pF	912	200	0.85±0.10	
MBARQ219SCG6R2□TRA01	QVS212 CG6R2□DHT		CG	C0G	6.2 p	±0.25pF, ±0.5pF	924	200	0.85±0.10	
MBARQ219SCG6R8□TRA01	QVS212 CG6R8□DHT	250	CG	C0G	6.8 p	±0.25pF, ±0.5pF	936	200	0.85±0.10	
MBARQ219SCG7R5□TRA01	QVS212 CG7R5□DHT		CG	C0G	7.5 p	±0.25pF, ±0.5pF	950	200	0.85±0.10	
MBARQ219SCG8R2□TRA01	QVS212 CG8R2□DHT		CG	C0G	8.2 p	±0.25pF, ±0.5pF	964	200	0.85±0.10	
MBARQ219SCG9R1□TRA01	QVS212 CG9R1□DHT		CG	C0G	9.1 p	±0.25pF, ±0.5pF	982	200	0.85±0.10	
MBARQ219SCG100JTRA01	QVS212 CG100JDHT		CG	C0G	10 p	±5%	1000	200	0.85±0.10	
MBARQ219SCG110JTRA01	QVS212 CG110JDHT		CG	C0G	11 p	±5%	1020	200	0.85±0.10	
MBARQ219SCG120JTRA01	QVS212 CG120JDHT		CG	C0G	12 p	±5%	1040	200	0.85±0.10	
MBARQ219SCG130JTRA01	QVS212 CG130JDHT		CG	C0G	13 p	±5%	1060	200	0.85±0.10	
MBARQ219SCG150JTRA01	QVS212 CG150JDHT		CG	C0G	15 p	±5%	1100	200	0.85±0.10	
MBARQ219SCG160JTRA01	QVS212 CG160JDHT		CG	C0G	16 p	±5%	1120	200	0.85±0.10	
MBARQ219SCG180JTRA01	QVS212 CG180JDHT		CG	C0G	18 p	±5%	1160	200	0.85±0.10	
MBARQ219SCG200JTRA01	QVS212 CG200JDHT		CG	C0G	20 p	±5%	1200	200	0.85±0.10	
MBARQ219SCG220JTRA01	QVS212 CG220JDHT		CG	C0G	22 p	±5%	1240	200	0.85±0.10	
MBARQ219SCG240JTRA01	QVS212 CG240JDHT		CG	C0G	24 p	±5%	1280	200	0.85±0.10	
MBARQ219SCG270JTRA01	QVS212 CG270JDHT		CG	C0G	27 p	±5%	1340	200	0.85±0.10	
MBARQ219SCG300JTRA01	QVS212 CG300JDHT		CG	C0G	30 p	±5%	1400	200	0.85±0.10	
MBARQ219SCG330JTRA01	QVS212 CG330JDHT		CG	C0G	33 p	±5%	1400	200	0.85±0.10	
MBARQ219SCG360JTRA01	QVS212 CG360JDHT		CG	C0G	36 p	±5%	1400	200	0.85±0.10	
MBARQ219SCG390JTRA01	QVS212 CG390JDHT		CG	C0G	39 p	±5%	1400	200	0.85±0.10	
MBARQ219SCG430JTRA01	QVS212 CG430JDHT		CG	C0G	43 p	±5%	1400	200	0.85±0.10	
MBARQ219SCG470JTRA01	QVS212 CG470JDHT		CG	C0G	47 p	±5%	1400	200	0.85±0.10	
MBARQ219SCG510JTRA01	QVS212 CG510JDHT		CG	C0G	51 p	±5%	1400	200	0.85±0.10	
MBARQ219SCG560JTRA01	QVS212 CG560JDHT		CG	C0G	56 p	±5%	1400	200	0.85±0.10	
MBARQ219SCG620JTRA01	QVS212 CG620JDHT		CG	C0G	62 p	±5%	1400	200	0.85±0.10	
MBARQ219SCG680JTRA01	QVS212 CG680JDHT		CG	C0G	68 p	±5%	1400	200	0.85±0.10	
MBARQ219SCG750JTRA01	QVS212 CG750JDHT		CG	C0G	75 p	±5%	1400	200	0.85±0.10	
MBARQ219SCG820JTRA01	QVS212 CG820JDHT		CG	C0G	82 p	±5%	1400	200	0.85±0.10	
MBARQ219SCG910JTRA01	QVS212 CG910JDHT		CG	C0G	91 p	±5%	1400	200	0.85±0.10	
MBARQ219SCG101JTRA01	QVS212 CG101JDHT		CG	C0G	100 p	±5%	1400	200	0.85±0.10	

■PACKAGING

①Minimum Quantity

●Taped package

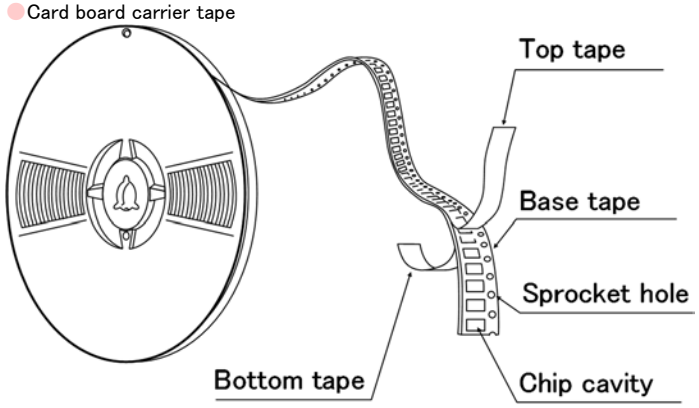
Type			Thickness		Standard Quantity[pcs]	
Code	JIS(mm)	EIA(inch)	[mm]	Code	Paper tape	Embossed tape
02	0201	008004	0.125	1	—	50000
04	0402	01005	0.2	2	—	40000
06	0603	0201	0.3	3	15000	—
1L	1005	0402	0.13	H	—	20000
			0.18	E	—	15000
			0.2	2	20000	—
			0.3	3	15000	—
10	1005	0402	0.5	5	10000	—
	0510 ※	0204	0.3	3	10000	—
16	1608	0603	0.45	K	4000	—
			0.7	7		
			0.8	8		
			0.8	8	3000 (Soft Termination)	3000 (Soft Termination)
	0816 ※	0306	0.5	5	—	4000
21	2012	0805	0.85	9	4000	—
			1.25	G	—	3000
			1.25	G	—	2000 (Soft Termination)
	1220 ※	0508	0.85	9	4000	—
31	3216	1206	0.85	9	4000	—
			1.15	Q	—	3000
			1.6	L	—	2000
32	3225	1210	0.85	9	—	2000
			1.15	Q		
			1.9	N		
			2.0 max	Y		
			2.5	M	—	500(T), 1000(P)
45	4532	1812	2.0 max	Y	—	1000
			2.5	M	—	500

注:※LW Reverse type (MSRL, MCRL, MBRL, MLRL, MMRL)

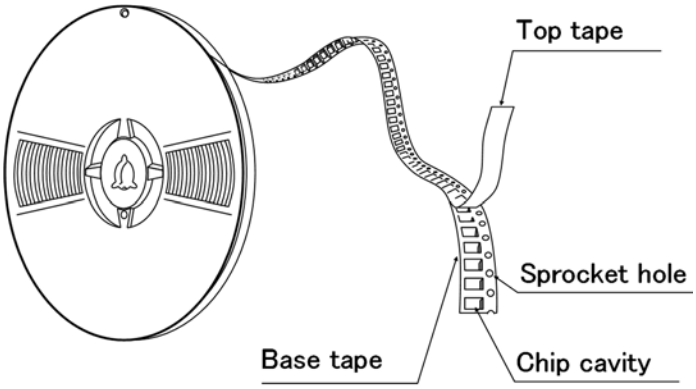
②Taping material

※No bottom tape for pressed carrier tape

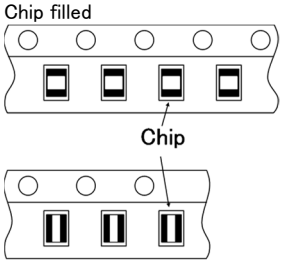
Card board carrier tape



Embossed tape



Chip filled



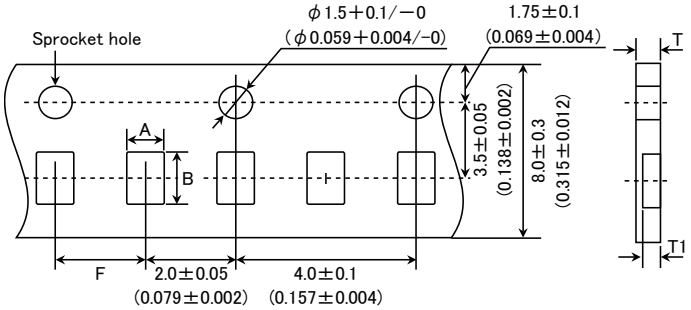
※ LW Reverse type.

③Representative taping dimensions

Paper Tape(8mm wide)

●Pressed carrier tape(2mm pitch)

Unit:mm(inch)



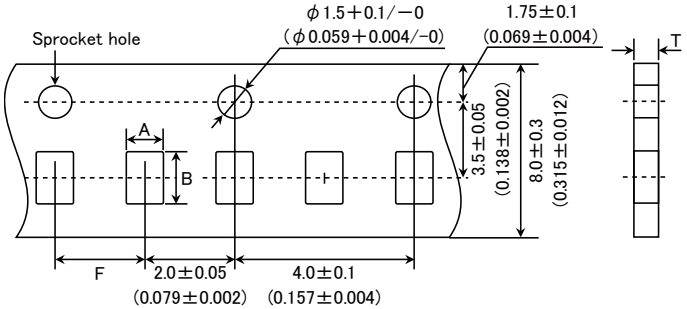
Type(EIA)	Chip Cavity		Insertion Pitch	Tape Thickness	
	A	B	F	T	T1
0603 (0201)	0.37	0.67	2.0±0.05	0.45max.	0.42max.
0510 (0204) ※	0.65	1.15			
1005 (0402) (*1 2)				0.4max.	0.3max.
1005 (0402) (*1 3)				0.45max.	0.42max.

Note *1 Thickness, 2:0.2mm , 3:0.3mm. ※ LW Reverse type.

Unit:mm

●Punched carrier tape (2mm pitch)

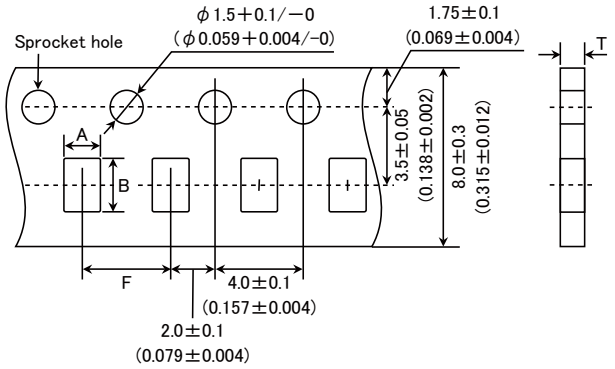
Unit:mm(inch)



Type(EIA)	Chip Cavity		Insertion Pitch	Tape Thickness
	A	B	F	T
1005 (0402)	0.65	1.15	2.0±0.05	0.8max.

Unit:mm

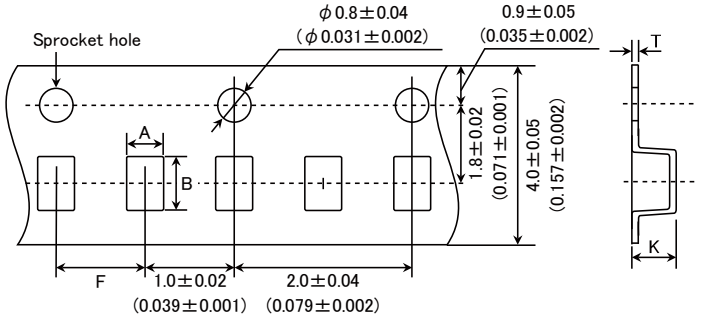
●Punched carrier tape (4mm pitch)　　Unit:mm(inch)



Type(EIA)	Chip Cavity		Insertion Pitch	Tape Thickness
	A	B	F	T
1608 (0603) 0816 (0306) ※	1.0	1.8	4.0±0.1	1.1max.
2012 (0805) 1220 (0508) ※	1.65	2.4		1.1max.
3216 (1206)	2.0	3.6		

Note:Taping size might be different depending on the size of the product. ※ LW Reverse type.　　Unit:mm

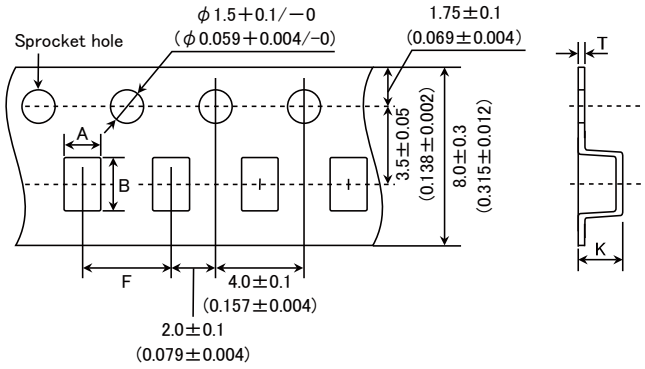
●Embossed tape(4mm wide)　　Unit:mm(inch)



Type(EIA)	Chip Cavity		Insertion Pitch	Tape Thickness	
	A	B	F	K	T
0201 (008004)	0.135	0.27	1.0±0.02	0.5max.	0.25max.
0402 (01005)	0.23	0.43			

Unit:mm

●Embossed tape(8mm wide)　　Unit:mm(inch)

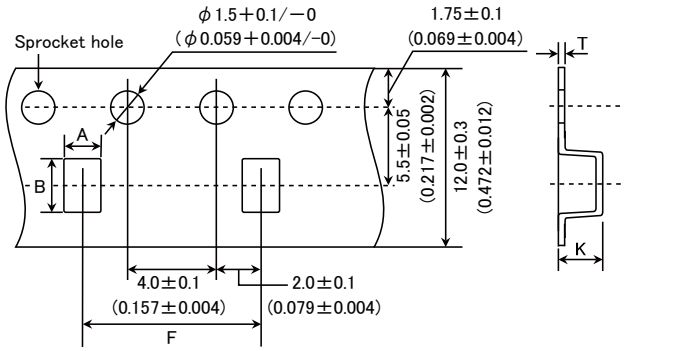


Type(EIA)	Chip Cavity		Insertion Pitch	Tape Thickness	
	A	B	F	K	T
1005 (0402)	0.6	1.1	2.0±0.1	0.6max	0.2±0.1
0816 (0306) ※	1.0	1.8	4.0±0.1	1.3max.	0.25±0.1
2012 (0805)	1.65	2.4		3.4max.	0.6max.
3216 (1206)	2.0	3.6			
3225 (1210)	2.8	3.6			

Note: ※ LW Reverse type.　　Unit:mm

Embossed tape (12mm wide)

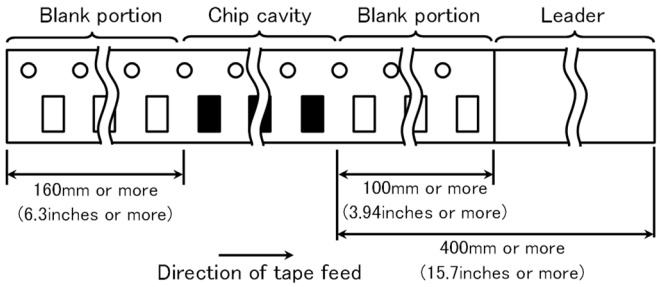
Unit : mm (inch)



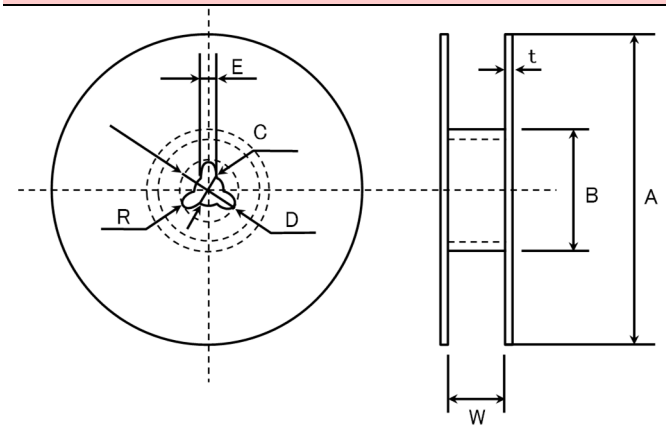
Type(EIA)	Chip Cavity		Insertion Pitch	Tape Thickness	
	A	B	F	K	T
3225 (1210)	3.1	4.0	8.0±0.1	4.0max.	0.6max.
4532 (1812)	3.7	4.9	8.0±0.1	4.0max.	0.6max.

Unit : mm

④Trailer and Leader



⑤Reel size



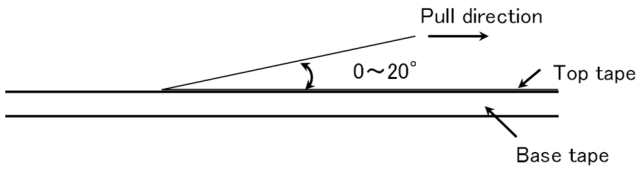
A	B	C	D	E	R
φ178±2.0	φ50min.	φ13.0±0.2	φ21.0±0.8	2.0±0.5	1.0

	T	W
4mm wide tape	1.5max.	5±1.0
8mm wide tape	2.5max.	10±1.5
12mm wide tape	2.5max.	14±1.5

Unit : mm

⑥Top Tape Strength

The top tape requires a peel-off force of 0.1 to 0.7N in the direction of the arrow as illustrated below.



Medium-High Voltage Multilayer Ceramic Capacitor for Telecommunications Infrastructure and Industrial Equipment
High frequency/Low loss Medium-High Voltage Multilayer Ceramic Capacitor for Telecommunications Infrastructure and Industrial Equipment
Medium-High Voltage Multilayer Ceramic Capacitor for Medical Devices classified as GHTF Class C (Japan Class III)
High frequency/Low loss Medium-High Voltage Multilayer Ceramic Capacitor for Medical Devices classified as GHTF Class C (Japan Class III)

■RELIABILITY DATA

1. Operating Temperature Range	
Specified Value	Temperature Compensating (High Frequency type) CG(C0G) : −55 to +125℃ High permittivity X7R, X7S : −55 to +125℃

2. Storage Temperature Range	
Specified Value	Temperature Compensating (High Frequency type) CG(C0G) : −55 to +125℃ High permittivity X7R, X7S : −55 to +125℃

3. Rated Voltage	
Specified Value	100VDC(Code:H), 250VDC(Code:Q), 630VDC(Code:S)

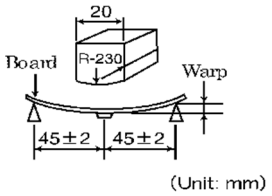
4. Withstanding Voltage(Between terminals)	
Specified Value	No breakdown or damage
Test Methods and Remarks	Applied voltage : Rated voltage(H) ×2.5, Rated voltage(Q) ×2, Rated voltage(S) ×1.2 Duration : 1 to 5sec. Carge/discharge current : 50mA max.

5. Insulation Resistance	
Specified Value	Temperature Compensating (High Frequency type) 10000MΩ min High permittivity 100MΩ μF or 10GΩ, whichever is smaller.
Test Methods and Remarks	Applied voltage : Rated voltage(H, Q), 500V(S) Duration : 60±5sec. Charge/discharge current : 50mA max.

6. Capacitance (Tolerance)	
Specified Value	Temperature Compensating (High Frequency type) C＜0.5pF(±0.05pF or ±0.1pF), 0.5pF≦C＜5pF(±0.1pF or ±0.25pF) 5pF≦C＜10(±0.25pF or ±0.5pF) C≧10pF(±5%)　(C:Nominal capacitance) High permittivity ±10%, ±20%
Test Methods and Remarks	Temperature Compensating (High Frequency type) Measuring frequency : 1MHz±10% Measuring voltage : 0.5 to 5Vrms Bias application : None High permittivity Measuring frequency : 1kHz±10% Measuring voltage : 1±0.2Vrms Bias application : None

7. Q or Dissipation Factor	
Specified Value	Temperature Compensating (High Frequency type) C＜30pF : Q≧800+20C C≧30pF : Q≧1400　(C: Normal Capacitance) High permittivity 3.5%max(H) 2.5%max(Q, S)
Test Methods and Remarks	Temperature Compensating (High Frequency type) Measuring frequency : 1MHz±10% Measuring voltage : 0.5 to 5Vrms Bas application : None High permittivity Measuring frequency : 1kHz±10% Measuring voltage : 1±0.2Vrms Bas application : None

8. Temperature Characteristic of Capacitance	
Specified Value	Temperature Compensating (High Frequency type) CG(C0G) : 0±30ppm(−55 to +125℃) High permittivity X7R :±15%(−55 to +125℃) X7S :±22%(−55 to +125℃)
Test Methods and Remarks	Temperature Compensating (High Frequency type) Capacitance at 25℃ and 85℃ shall be measured in thermal equilibrium, and the temperature characteristic shall be calculated from the following equation. $\frac{(C_{85}-C_{25})}{C_{25}\times\Delta T}\times 10^6\times[\mathrm{ppm/℃}]$ High permittivity Capacitance value at each step shall be measured in thermal equilibrium, and the temperature characteristic shall be calculated from the following equation. Step / Temperature 1 / Minimum operating temperature 2 / 25℃ 3 / Maximum operating temperature $\frac{(C-C_2)}{C_2}\times 100(\%)$ C : Capacitance value in Step 1 or Step 3 C2 : Capacitance value in Step 2

9. Deflection	
Specified Value	Temperature Compensating (High Frequency type) Appearance : No abnormality Capacitance change :±5% or ±0.5pF, whichever is larger. High permittivity Appearance : No abnormality Capacitance change : Within±10%
Test Methods and Remarks	Warp : 1mm (Soft Termination type:3mm) Duration : 10sec. Test board : Glass epoxy-resin substrate Thickness : 1.6mm  (Unit: mm) Capacitance measurement shall be conducted with the board bent.

10. Adhesive Strength of Terminal Electrodes	
Specified Value	No terminal separation or its indication.
Test Methods and Remarks	Applied force : 5N Duration : 30±5sec. (Soft Termination type: 10±1sec)

11. Vibration	
Specified Value	Initial performance shall be satisfied.
Test Methods and Remarks	Preconditioning : Thermal treatment (at 150℃ for 1hr) Note1 (Only High permittivity) Frequency range : 10 to 55 Hz Overall amplitude : 1.5 mm Sweeping method : 10 to 55 to 10 Hz for 1 min Two hours each in X, Y, Z directions: 6 hrs in total

12. Solderability	
Specified Value	At least 95% of terminal electrode is covered by new solder
Test Methods and Remarks	

	Eutectic solder	Lead-free solder
Solder type	H60A or H63A	Sn-3.0Ag-0.5Cu
Solder temperature	230±5℃	245±3℃
Duration	4±1 sec.	

13. Resistance to Soldering	
Specified Value	Temperature Compensating (High Frequency type) Appearance : No abnormality Capacitance change : Within ±2.5% or ±0.25pF, whichever is larger. Insulation resistance : Initial value Withstanding voltage (between terminals) : No abnormality High permittivity Appearance : No abnormality Capacitance change : Within±15%(H), ±10%(Q, S) Dissipation factor : Initial value Insulation resistance : Initial value Withstanding voltage (between terminals) : No abnormality
Test Methods and Remarks	Preconditioning : Thermal treatment (at 150℃ for 1hr) Note1 (Only High permittivity) Solder temperature : 270±5℃ Duration : 3±0.5sec. Preheating conditions : 80 to 100℃, 2 to 5 min. 150 to 200℃, 2 to 5min. Recovery : 24±2hrs under the standard condition Note3

14. Temperature Cycle (Thermal Shock)

Specified Value

Temperature Compensating (High Frequency type)

Appearance	: No abnormality
Capacitance change	: Within ±2.5% or ±0.25pF, whichever is larger.
Insulation resistance	: Initial value
Withstanding voltage	(between terminals) : No abnormality

High permittivity

Appearance	: No abnormality
Capacitance change	: Within±15%(H), ±7.5%(Q, S)
Dissipation factor	: Initial value
Insulation resistance	: Initial value
Withstanding voltage	(between terminals) : No abnormality

Test Methods and Remarks

Preconditioning : Thermal treatment (at 150℃ for 1hr) Note1

Conditions for 1 cycle

Step	temperature(℃)	Time(min.)
1	Minimum operating temperature	30±3min.
2	Normal temperature	2 to 3min.
3	Maximum operating temperature	30±3min.
4	Normal temperature	2 to 3min.

Number of cycles : 50 times

Recovery : 24±2hrs under the standard condition Note3

15. Humidity (Steady state)

Specified Value

Temperature Compensating (High Frequency type)

Appearance	: No abnormality
Capacitance change	: Within ±5% or ±0.5pF, whichever is larger.
Insulation resistance	: 1000MΩmin

High permittivity

Appearance	: No abnormality
Capacitance change	: Within±15%
Dissipation factor	: 7%max(H), 5%max(Q, S).
Insulation resistance	: 25MΩ μF or 1000MΩ, whichever is smaller.

Test Methods and Remarks

Preconditioning	: Thermal treatment(at 150℃ for 1hr) Note1 (Only High permittivity)
Temperature	: 40±2℃
Humidity	: 90 to 95%RH
Duration	: 500 +24/−0 hrs
Recovery	: 24±2hrs under the standard condition Note3

16. Humidity Loading

Specified Value

Temperature Compensating (High Frequency type)

Appearance	: No abnormality
Capacitance change	: C≦2.0pF :±0.4pF 2.0pF＜C＜10pF : ±0.75pF C≧10pF :±7.5% (C: Nominal capacitance)
Insulation resistance	: 500MΩmin

High permittivity

Appearance	: No abnormality
Capacitance change	: Within±15%
Dissipation factor	: 7%max(H), 5%max(Q, S).
Insulation resistance	: 10MΩ μF or 500MΩ, whichever is smaller.

Test Methods and Remarks

Preconditioning	: Voltage treatment Note2 (Only High permittivity)
Temperature	: 60±2℃
Humidity	: 90 to 95%RH
Duration	: 500 +24/−0 hrs
Applied voltage	: Rated voltage
Charge/discharge current	: 50mA max.
Recovery	: 24±2hrs under the standard condition Note3

17. High Temperature Loading		
Specified Value	Temperature Compensating (High Frequency type)	
	Appearance	: No abnormality
	Capacitance change	: Within ±3% or ±0.3pF, whichever is larger.
	Insulation resistance	:1000MΩmin
	High permittivity	
	Appearance	: No abnormality
	Capacitance change	: Within±15%
	Dissipation factor	: 7%max(H), 5%max(Q, S).
	Insulation resistance	: 50MΩ μF or 1000MΩ, whichever is smaller.
Test Methods and Remarks	Preconditioning	: Voltage treatment Note2 (Only High permittivity)
	Temperature	: Maximum operating temperature
	Duration	: 1000 +24/−0 hrs
	Applied voltage	: Rated voltage×2(H, Q(High frequency / low loss type))
		Rated voltage×1.5(Q(Excluding High frequency / low loss type)), Rated voltage×1.2(S)
	Charge/discharge current	: 50mA max.
	Recovery	: 24±2hrs under the standard condition Note3

Note1 Thermal treatment : Initial value shall be measured after test sample is heat-treated at 150+0/−10℃ for an hour and kept at room temperature for 24±2hours.

Note2 Voltage treatment : Initial value shall be measured after test sample is voltage-treated for an hour at both the temperature and voltage specified in the test conditions, and kept at room temperature for 24±2hours.

Note3 Standard condition : Temperature: 5 to 35℃, Relative humidity: 45 to 85 % RH, Air pressure: 86 to 106kPa
When there are questions concerning measurement results, in order to provide correlation data, the test shall be conducted under the following condition.
Temperature: 20±2℃, Relative humidity: 60 to 70 % RH, Air pressure: 86 to 106kPa
Unless otherwise specified, all the tests are conducted under the "standard condition".

■PRECAUTIONS

1. Circuit Design

Precautions

◆Verification of operating environment, electrical rating and performance

1. A malfunction of equipment in fields such as medical, aerospace, nuclear control, etc. may cause serious harm to human life or have severe social ramifications.
   Therefore, any capacitors to be used in such equipment may require higher safety and reliability, and shall be clearly differentiated from them used in general purpose applications.

◆Operating Voltage (Verification of Rated voltage)

1. The operating voltage for capacitors must always be their rated voltage or less.
   If an AC voltage is loaded on a DC voltage, the sum of the two peak voltages shall be the rated voltage or less.
   For a circuit where an AC or a pulse voltage may be used, the sum of their peak voltages shall also be the rated voltage or less.
2. Even if an applied voltage is the rated voltage or less reliability of capacitors may be deteriorated in case that either a high frequency AC voltage or a pulse voltage having rapid rise time is used in a circuit.

2. PCB Design

Precautions

◆Pattern configurations (Design of Land-patterns)

1. When capacitors are mounted on PCBs, the amount of solder used (size of fillet) can directly affect the capacitor performance. Therefore, the following items must be carefully considered in the design of land patterns:
   (1) Excessive solder applied can cause mechanical stresses which lead to chip breaking or cracking. Therefore, please consider appropriate land-patterns for proper amount of solder.
   (2) When more than one component are jointly soldered onto the same land, each component's soldering point shall be separated by solder-resist.

◆Pattern configurations (Capacitor layout on PCBs)

After capacitors are mounted on boards, they can be subjected to mechanical stresses in subsequent manufacturing processes (PCB cutting, board inspection, mounting of additional parts, assembly into the chassis, wave soldering of the boards, etc.). For this reason, land pattern configurations and positions of capacitors shall be carefully considered to minimize stresses.

Technical considerations

◆Pattern configurations (Design of Land-patterns)

The following diagrams and tables show some examples of recommended land patterns to prevent excessive solder amounts.

(1) Recommended land dimensions for typical chip capacitors

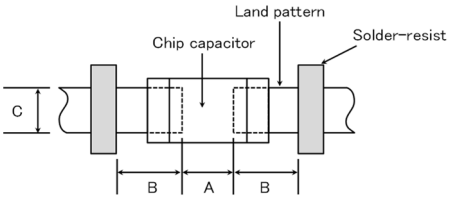
●Multilayer Ceramic Capacitors : Recommended land dimensions

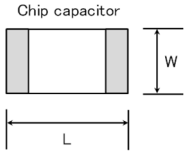
(unit: mm)

Wave-soldering

Type		1608	2012	3216	3225
Size	L	1.6	2.0	3.2	3.2
	W	0.8	1.25	1.6	2.5
A		0.8 to 1.0	1.0 to 1.4	1.8 to 2.5	1.8 to 2.5
B		0.5 to 0.8	0.8 to 1.5	0.8 to 1.7	0.8 to 1.7
C		0.6 to 0.8	0.9 to 1.2	1.2 to 1.6	1.8 to 2.5

Land patterns for PCBs





Reflow-soldering

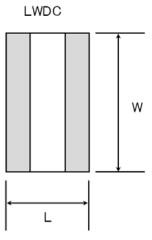
Type		0201	0402	0603	1005	1608	2012	3216	3225	4532
Size	L	0.25	0.4	0.6	1.0	1.6	2.0	3.2	3.2	4.5
	W	0.125	0.2	0.3	0.5	0.8	1.25	1.6	2.5	3.2
A		0.095～0.135	0.15～0.25	0.20～0.30	0.45～0.55	0.6～0.8	0.8～1.2	1.8～2.5	1.8～2.5	2.5～3.5
B		0.085～0.125	0.10～0.20	0.20～0.30	0.40～0.50	0.6～0.8	0.8～1.2	1.0～1.5	1.0～1.5	1.5～1.8
C		0.110～0.150	0.15～0.30	0.25～0.40	0.45～0.55	0.6～0.8	0.9～1.6	1.2～2.0	1.8～3.2	2.3～3.5

Note : Recommended land size might be different according to the allowance of the size of the product.

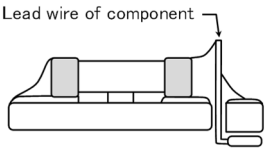
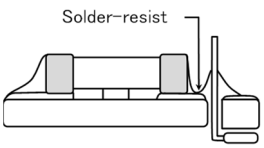
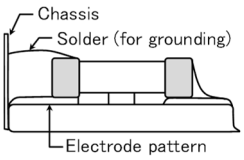
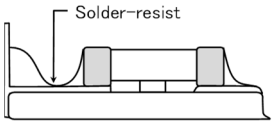
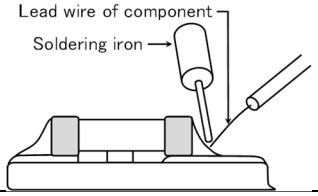
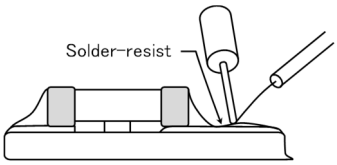
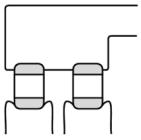
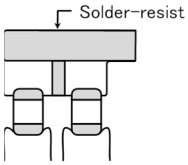
●LWDC: Recommended land dimensions for reflow-soldering

(unit: mm)

Type		0510	0816	1220
Size	L	0.52	0.8	1.25
	W	1.0	1.6	2.0
A		0.18～0.22	0.25～0.3	0.5～0.7
B		0.2～0.25	0.3～0.4	0.4～0.5
C		0.9～1.1	1.5～1.7	1.9～2.1

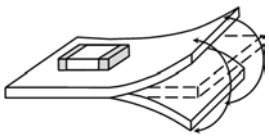
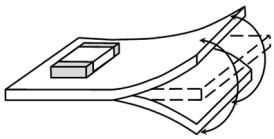


(2) Examples of good and bad solder application

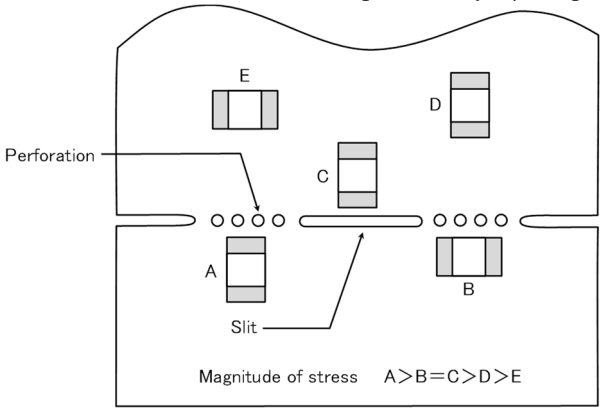
Item	Not recommended	Recommended
Mixed mounting of SMD and leaded components		
Component placement close to the chassis		
Hand-soldering of leaded components near mounted components		
Horizontal component placement		

◆Pattern configurations (Capacitor layout on PCBs)

1-1. The following is examples of good and bad capacitor layouts ; capacitors shall be located to minimize any possible mechanical stresses from board warp or deflection.

Items	Not recommended	Recommended
Deflection of board		 Place the product at a right angle to the direction of the anticipated mechanical stress.

1-2. The amount of mechanical stresses given will vary depending on capacitor layout. Please refer to diagram below.



1-3. When PCB is split, the amount of mechanical stress on the capacitors can vary according to the method used. The following methods are listed in order from least stressful to most stressful: push-back, slit, V-grooving, and perforation. Thus, please consider the PCB, split methods as well as chip location.

3. Mounting

Precautions

◆Adjustment of mounting machine

1. When capacitors are mounted on PCB, excessive impact load shall not be imposed on them.
2. Maintenance and inspection of mounting machines shall be conducted periodically.

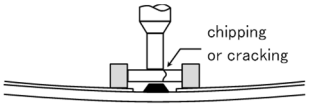
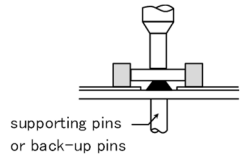
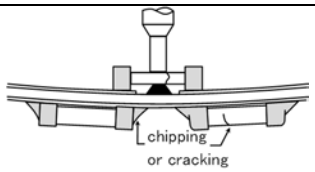
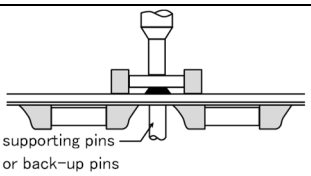
◆Selection of Adhesives

1. When chips are attached on PCBs with adhesives prior to soldering, it may cause capacitor characteristics degradation unless the following factors are appropriately checked : size of land patterns, type of adhesive, amount applied, hardening temperature and hardening period. Therefore, please contact us for further information.

Technical considerations

◆Adjustment of mounting machine

1. When the bottom dead center of a pick-up nozzle is too low, excessive force is imposed on capacitors and causes damages. To avoid this, the following points shall be considerable.
   (1) The bottom dead center of the pick-up nozzle shall be adjusted to the surface level of PCB without the board deflection.
   (2) The pressure of nozzle shall be adjusted between 1 and 3 N static loads.
   (3) To reduce the amount of deflection of the board caused by impact of the pick-up nozzle, supporting pins or back-up pins shall be used on the other side of the PCB. The following diagrams show some typical examples of good and bad pick-up nozzle placement:

Item	Improper method	Proper method
Single-sided mounting		
Double-sided mounting		

2. As the alignment pin is worn out, adjustment of the nozzle height can cause chipping or cracking of capacitors because of mechanical impact on the capacitors.
   To avoid this, the monitoring of the width between the alignment pins in the stopped position, maintenance, check and replacement of the pin shall be conducted periodically.

◆Selection of Adhesives

Some adhesives may cause IR deterioration. The different shrinkage percentage of between the adhesive and the capacitors may result in stresses on the capacitors and lead to cracking. Moreover, too little or too much adhesive applied to the board may adversely affect components. Therefore, the following precautions shall be noted in the application of adhesives.

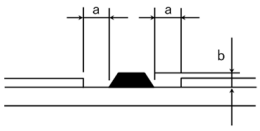
(1) Required adhesive characteristics
   a. The adhesive shall be strong enough to hold parts on the board during the mounting & solder process.
   b. The adhesive shall have sufficient strength at high temperatures.
   c. The adhesive shall have good coating and thickness consistency.
   d. The adhesive shall be used during its prescribed shelf life.
   e. The adhesive shall harden rapidly.
   f. The adhesive shall have corrosion resistance.
   g. The adhesive shall have excellent insulation characteristics.
   h. The adhesive shall have no emission of toxic gasses and no effect on the human body.

(2) The recommended amount of adhesives is as follows;

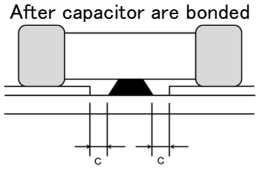
[Recommended condition]

Figure	2012/3216 case sizes as examples
a	0.3mm min
b	100 to 120 μm
c	Adhesives shall not contact land

Amount adhesive



After capacitor are bonded



4. Soldering

Precautions

◆Selection of Flux

Since flux may have a significant effect on the performance of capacitors, it is necessary to verify the following conditions prior to use;

(1) Flux used shall be less than or equal to 0.1 wt%(in Cl equivalent) of halogenated content. Flux having a strong acidity content shall not be applied.
(2) When shall capacitors are soldered on boards, the amount of flux applied shall be controlled at the optimum level.
(3) When water-soluble flux is used, special care shall be taken to properly clean the boards.

◆Soldering

Temperature, time, amount of solder, etc. shall be set in accordance with their recommended conditions.
Sn-Zn solder paste can adversely affect MLCC reliability.
Please contact us prior to usage of Sn-Zn solder.

Technical considerations

◆Selection of Flux

1-1. When too much halogenated substance(Chlorine, etc.) content is used to activate flux, or highly acidic flux is used, it may lead to corrosion of terminal electrodes or degradation of insulation resistance on the surfaces of the capacitors.
1-2. Flux is used to increase solderability in wave soldering. However if too much flux is applied, a large amount of flux gas may be emitted and may adversely affect the solderability. To minimize the amount of flux applied, it is recommended to use a flux-bubbling system.
1-3. Since the residue of water-soluble flux is easily dissolved in moisture in the air, the residues on the surfaces of capacitors in high humidity conditions may cause a degradation of insulation resistance and reliability of the capacitors. Therefore, the cleaning methods

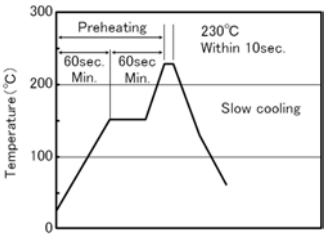
and the capability of the machines used shall also be considered carefully when water-soluble flux is used.

◆Soldering

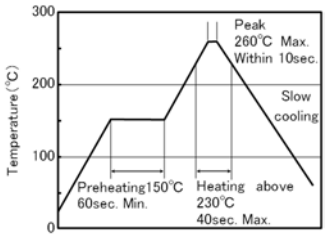
- Ceramic chip capacitors are susceptible to thermal shock when exposed to rapid or concentrated heating or rapid cooling.
- Therefore, the soldering must be conducted with great care so as to prevent malfunction of the components due to excessive thermal shock.
- Preheating : Capacitors shall be preheated sufficiently, and the temperature difference between the capacitors and solder shall be within 130℃.
- Cooling : The temperature difference between the capacitors and cleaning process shall not be greater than 100℃.

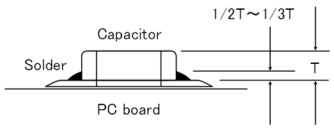
[Reflow soldering]

【Recommended conditions for eutectic soldering】



【Recommended condition for Pb-free soldering】





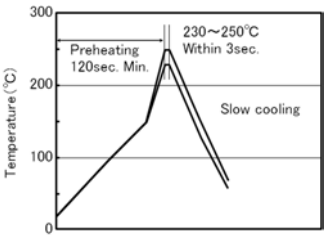
Caution

①The ideal condition is to have solder mass (fillet) controlled to 1/2 to 1/3 of the thickness of a capacitor.

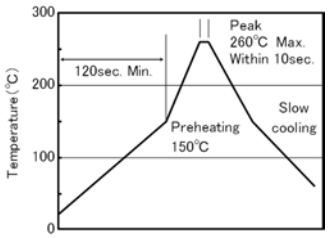
②Because excessive dwell times can adversely affect solderability, soldering duration shall be kept as close to recommended times as possible. soldering for 2 times.

[Wave soldering]

【Recommended conditions for eutectic soldering】



【Recommended condition for Pb-free soldering】

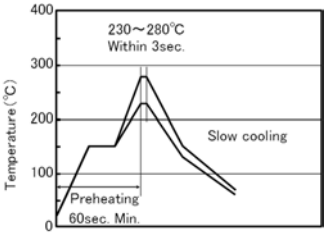


Caution

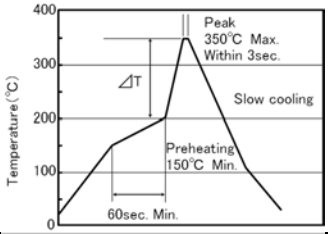
①Wave soldering must not be applied to capacitors designated as for reflow soldering only. soldering for 1 times.

[Hand soldering]

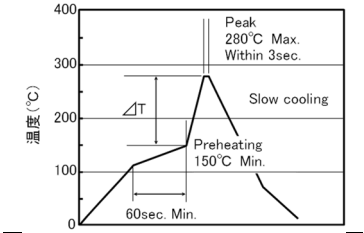
【Recommended conditions for eutectic soldering】



【Recommended condition for Pb-free soldering】



	⊿T
3216type or less	⊿T≦150℃



	⊿T
3225type or more	⊿T≦130℃

Caution

①Use a 50W soldering iron with a maximum tip diameter of 1.0 mm.

②The soldering iron shall not directly touch capacitors. soldering for 1 times.

5. Cleaning	
Precautions	◆Cleaning conditions 1. When PCBs are cleaned after capacitors mounting, please select the appropriate cleaning solution in accordance with the intended use of the cleaning. (e.g. to remove soldering flux or other materials from the production process.) 2. Cleaning condition shall be determined after it is verified by using actual cleaning machine that the cleaning process does not affect capacitor's characteristics.
Technical considerations	1. The use of inappropriate cleaning solutions can cause foreign substances such as flux residue to adhere to capacitors or deteriorate their outer coating, resulting in a degradation of the capacitor's electrical properties (especially insulation resistance). 2. Inappropriate cleaning conditions(insufficient or excessive cleaning) may adversely affect the performance of the capacitors. In the case of ultrasonic cleaning, too much power output can cause excessive vibration of PCBs which may lead to the cracking of capacitors or the soldered portion, or decrease the terminal electrodes' strength. Therefore, the following conditions shall be carefully checked; Ultrasonic output : 20 W/ℓ or les Ultrasonic frequency : 40 kHz or less Ultrasonic washing period : 5 min. or less

6. Resin coating and mold	
Precautions	1. With some type of resins, decomposition gas or chemical reaction vapor may remain inside the resin during the hardening period or while left under normal storage conditions resulting in the deterioration of the capacitor's performance. 2. When a resin's hardening temperature is higher than capacitor's operating temperature, the stresses generated by the excessive heat may lead to damage or destruction of capacitors. The use of such resins, molding materials etc. is not recommended.

7. Handling	
Precautions	◆Splitting of PCB 1. When PCBs are split after components mounting, care shall be taken so as not to give any stresses of deflection or twisting to the board. 2. Board separation shall not be done manually, but by using the appropriate devices. ◆Mechanical considerations Be careful not to subject capacitors to excessive mechanical shocks. (1)If ceramic capacitors are dropped onto a floor or a hard surface, they shall not be used. (2)Please be careful that the mounted components do not come in contact with or bump against other boards or components.

8. Storage conditions	
Precautions	◆Storage 1. To maintain the solderability of terminal electrodes and to keep packaging materials in good condition, care must be taken to control temperature and humidity in the storage area. Humidity should especially be kept as low as possible. ・Recommended conditions Ambient temperature : Below 30℃ Humidity : Below 70% RH The ambient temperature must be kept below 40℃. Even under ideal storage conditions, solderability of capacitor is deteriorated as time passes, so capacitors shall be used within 6 months from the time of delivery. ・Ceramic chip capacitors shall be kept where no chlorine or sulfur exists in the air. 2. The capacitance values of high dielectric constant capacitors will gradually decrease with the passage of time, so care shall be taken to design circuits. Even if capacitance value decreases as time passes, it will get back to the initial value by a heat treatment at 150℃ for 1hour.
Technical considerations	If capacitors are stored in a high temperature and humidity environment, it might rapidly cause poor solderability due to terminal oxidation and quality loss of taping/packaging materials. For this reason, capacitors shall be used within 6 months from the time of delivery. If exceeding the above period, please check solderability before using the capacitors.

※RCR-2335B(Safety Application Guide for fixed ceramic capacitors for use in electronic equipment)is published by JEITA.
Please check the guide regarding precautions for deflection test, soldering by spot heat, and so on.